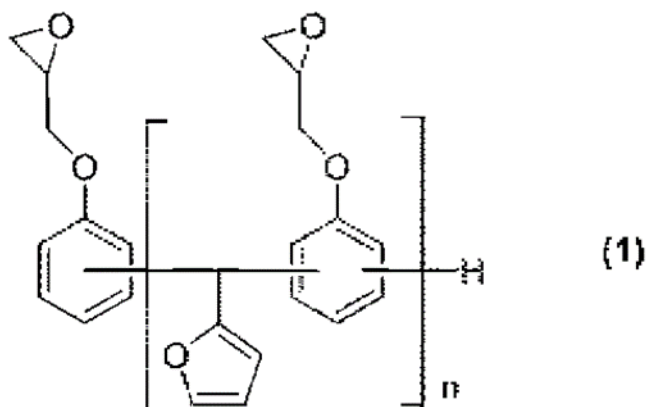


ABSTRACT

The present invention provides: a curable resin composition having a high degree of biomass and having excellent high heat resistance and low dielectric properties; and a cured
5 product of the curable resin composition. The curable resin composition comprises an epoxy resin represented by formula (1) and an acid anhydride curing agent comprising a biomass-derived compound. (In formula (1), n is the average number of repeating units, and represents a real number within the range $1 < n < 15$.)



10

FIG. 1